



 Part :
 SPI201610P_201612P
 Version :
 B_3.0
 Page :
 1/1

SPI252010P_252012P series

INDEX

SHAPES AND DIMENSIONS	1
PART NUMBER CODE	1
ELECTRICAL CHARACTERISTICS	2
REEL DIMENSIONS AND PACKAGING QUANTITY	4
NOTE	5



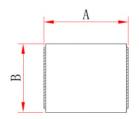


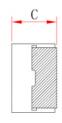


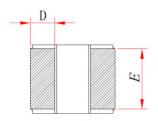
SPI252010P_252012P series

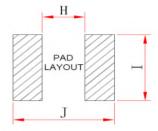
Shielded SMT Power Inductor SPI201610P_201612P_252010P_252012P series

■ SHAPES AND DIMENSIONS









Recommend PAD Layout

Item	Α	В	С	D	E	Н	I	J
SPI201610P	2.0±0.2	1.6±0.2	1.0 Max	0.5±0.2	1.44	0.9	1.6	2.3
SPI201612P	2.0±0.2	1.6±0.2	1.2 Max	0.5±0.2	1.44	0.9	1.6	2.3
SPI252010P	2.5±0.2	2.0±0.2	1.0 Max	0.6±0.2	1.84	1.2	2.0	2.8
SPI252012P	2.5±0.2	2.0±0.2	1.2 Max	0.6±0.2	1.84	1.2	2.0	2.8

Marking:

NO Marking





■ PART NUMBER CODE

<u>SPI 201610 P - 1R0 M A</u>
1 2 3 4 5 6

- 1. Series Name
- 2. Size Code
- 3. Special code: Extra low DCR
- 4. Inductance(R=Decimal Point) Unit : μH; 1R0 =1.0uH
- 5. Inductance tolerance: "M"±20%
- 6. Soldering: A=Lead Free







SPI252010P_252012P series

■ ELECTRICAL CHARACTERISTICS

- 1. Test equipments
 - 1.1. L: Agilent E4980 Precision LCR Meter (Upgraded version of Agilent HP4284A) with HP42841A Current Source
 - 1.2. DCR: Milli-ohm meter
 - 1.3. Saturation Current (Isat): The DC current will cause L0 to drop approximately 30% typical.
 - 1.4. Temperature Rise Current (Irms): The DC current will cause the coil temperature rise approximately $\triangle T$ of 40°C.
 - 1.5. Operating temperature: -55°C to 125°C
- * Equivalent measurement equipment may be used.







SPI252010P_252012P series

2. Part Number and Characteristics Table

Dest No	Inductance L(uH)	Tolerance	DCR(mΩ)		Isat(A)		Irms(A)	
Part No.		(±%)	Тур.	Max.	Тур.	Max.	Тур.	Max.
SPI201610P-R24MA	0.24	20	17	20.5	6	5.4	4.7	4.2
SPI201610P-R33MA	0.33	20	25	30	5.2	4.7	4.1	3.6
SPI201610P-R47MA	0.47	20	32	38	5	4.4	3.8	3.3
SPI201610P-R68MA	0.68	20	42	48	4	3.6	3.2	2.7
SPI201610P-1R0MA	1	20	60	68	2.9	2.4	2.6	2.3
SPI201610P-1R5MA	1.5	20	100	116	2.4	1.8	2.1	1.8
SPI201610P-2R2MA	2.2	20	147	163	1.9	1.6	1.8	1.6
SPI201612P-R24MA	0.24	20	15	19	6.5	5.6	5.2	4.4
SPI201612P-R33MA	0.33	20	22	26	5.4	4.6	4.6	3.9
SPI201612P-R47MA	0.47	20	25	30	4.5	3.8	4	3.4
SPI201612P-R68MA	0.68	20	36	44	3.8	3.2	3.5	3
SPI201612P-1R0MA	1	20	50	60	2.9	2.5	3	2.5
SPI201612P-1R5MA	1.5	20	86	104	2.3	2	2.2	2
SPI201612P-2R2MA	2.2	20	120	144	2	1.65	1.8	1.6
SPI252010P-R22MA	0.22	20	15	17	8.5	7	6.5	5.5
SPI252010P-R33MA	0.33	20	16.5	20	6.5	5.8	5.5	4.8
SPI252010P-R47MA	0.47	20	23	29	5.5	5	4.1	3.6
SPI252010P-R68MA	0.68	20	36	44	4.6	4.1	3.6	3.1
SPI252010P-1R0MA	1	20	44	53	4	3.6	3.4	3
SPI252010P-1R5MA	1.5	20	61	70	3	2.5	2.8	2.4
SPI252010P-2R2MA	2.2	20	90	105	2.6	2.2	2	1.8
SPI252012P-R22MA	0.22	20	11	13	8.5	7	10	8
SPI252012P-R33MA	0.33	20	15	16.5	7	5.8	5.8	5.2
SPI252012P-R47MA	0.47	20	20	25	6	5	4.8	4.2
SPI252012P-R68MA	0.68	20	30	34	4.6	4	3.9	3.5
SPI252012P-1R0MA	1	20	38	45	4.3	3.9	3.7	3.2
SPI252012P-1R5MA	1.5	20	53	60	3	2.6	2.9	2.6
SPI252012P-2R2MA	2.2	20	78	90	2.7	2.3	2.4	2
SPI252012P-3R3MA	3.3	20	135.9	144	2	1.8	1.75	1.55

Note 1: Referenced ambient temperature 20° C.

Note 2: Test Condition: 1MHz, 1.0 Vrms.

Note 3: Isat (Typ): DC current (A) that will cause L0 to drop approximately 30%

Isat (Max): DC current (A) that will cause L0 to drop 30% Max

Irms (Typ): DC current (A) that will cause an approximate ΔT of 40°C

Irms (Max): DC current (A) that will cause an ΔT of 40°C Max

Note 4: Operating Temperature range includes self-temperature rise

Note 5: The rated current as listed is either the saturation current or the heating current depending on which value is lower.

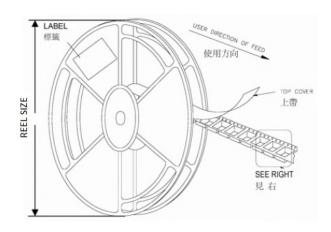


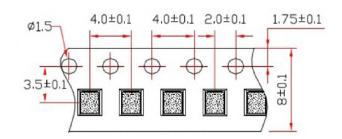




SPI252010P_252012P series

■ REEL DIMENSIONS AND PACKAGING QUANTITY





Unit: mm

TYPE	W	Р	REEL SIZE	PCS / REEL
SPI2016_2520P series	8	4	178 mm (7")	3000







SPI252010P 252012P series

■ NOTE

1. Storage condition:

To maintain the solderability of terminal electrodes:

- 1.1. Temperature and humidity conditions: 5~35°C and 35~70%RH.
- 1.2. Storage life: 12 months Max. If product is preserved for more than 1 year, the solderability of their terminals may be deteriorated.
- 1.3. The packaging material should be kept where no chlorine or corrosive gas environment. (example: salt, sulfur, acid, etc..)

2. Transportation

- 2.1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2.2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 2.3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

3. Application

The products listed on this datasheet are intended for use in general electronic equipment under a normal operation and use condition.

The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. ETC shall not be held liable for any malfunction or breakdown caused by using product in the condition which is inconsistent with that recommended by ETC.

(1)Military equipment. (2)Medical equipment. (3)Aerospace equipment. (4) Other applications that are not considered general-purpose applications.

